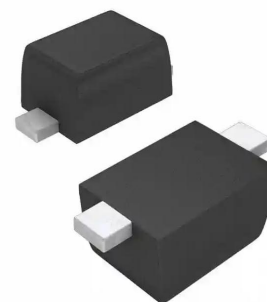




## 1. Features

- Small surface mounting type
- Low  $I_R$
- High reliability

SOD523



## 2. Mechanical Data

- Case:Molded Plastic,SOD-523.
- Epoxy:UL 94V-0 rate flame retardant.
- Terminals:Plated Leads Solderable per MIL-STD-750, Method-2026.
- Marking:B
- Marking:marked on body.



## 3. Maximum Ratings

Electrical Characteristics Rating at 25°C ambient temperature unless otherwise specified.

Characteristic	Symbol	Value	Unit
DC reverse voltage	$V_R$	30	V
Mean rectifying current	$I_O$	200	mA
Non-Repetitive Peak Forward Current $t = 8.3 \text{ ms}$	$I_{FSM}$	1	A
Power Dissipation	$P_D$	150	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	667	°C/W
Junction Temperature	$T_J$	-40 to+125	°C
Storage Temperature Range	$T_{slg}$	-55 to+150	°C

## 4. Electrical Characteristics ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameters	Symbol	Cindition	Min	TYP	Max	Unit
Forward Voltage	$V_F$	$I_F = 200\text{mA}$	-	-	600	mV
Reverse Current	$I_R$	$V_R = 10\text{V}$	-	-	1.0	$\mu\text{A}$



### 5. Rating And Characteristic Curves

Fig.1 Forward Characteristics

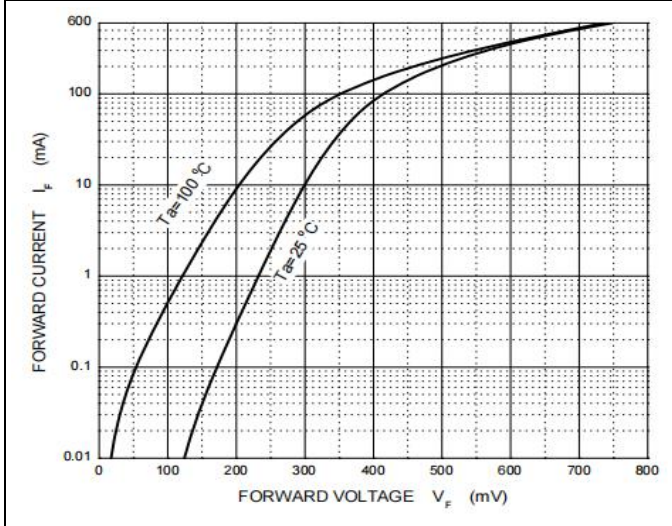


Fig.2 Reverse Characteristics

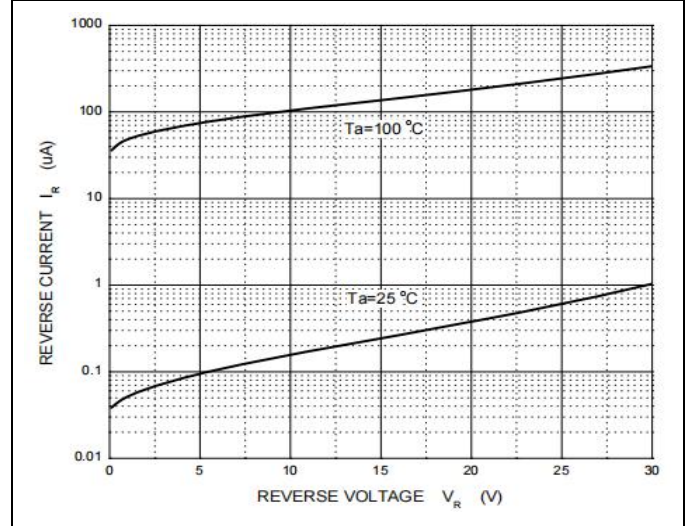


Fig.3 Capacitance Characteristics Per Diode

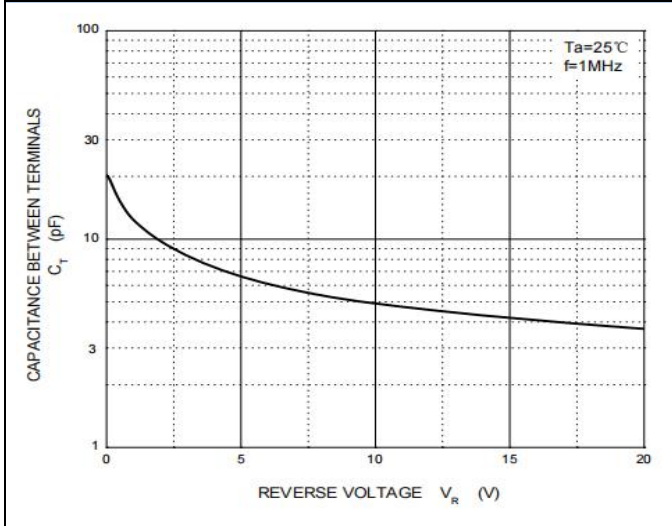
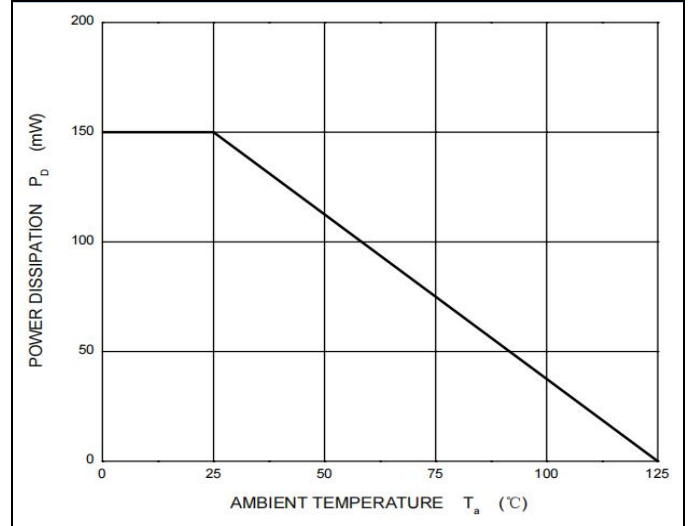
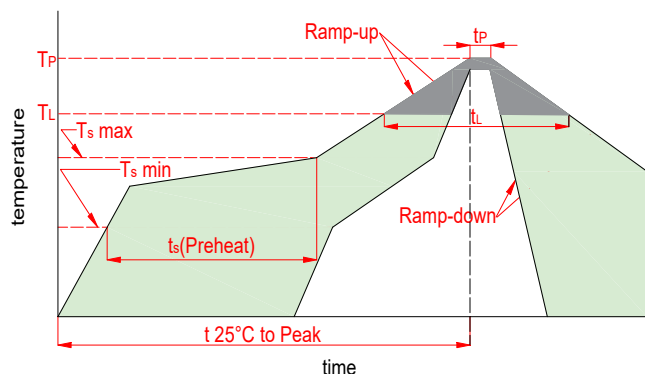


Fig.4 Power Derating Curve



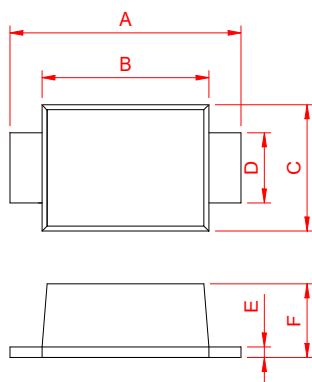


## 6. Soldering Parameters



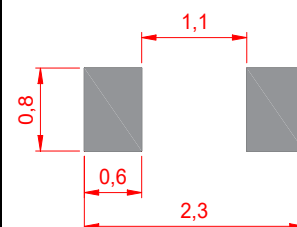
Reflow Condition		Lead-free
Pre Heat	Temp. min( $T_s$ (min))	150°C
	Temp. max( $T_s$ (min))	200°C
	Time(min to max)( $t_s$ )	60~120s
Aver. ramp up rate(Liquidus Temp.)( $T_L$ )to peak		3°C/s max
$T_s$ (max) to $T_L$ -Ramp-up Rate		3°C/s max
Reflow	Temp.( $T_L$ )(Liquidus)	217°C
	Temp.( $t_L$ )(Liquidus)	60~150s
Peak Temp.( $T_P$ )		260 <sup>+0/-5</sup> °C
Time within actual peak Temp.( $t_p$ )		30s max
Ramp-down Rate		6°C/s max
Time 25°C to peak Tempe.( $T_p$ )		8 minutes max
Do not exceed		260°C

## 7. Dimensions

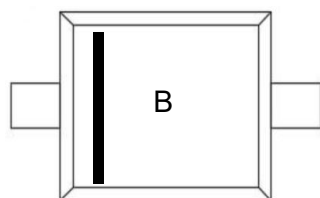


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.059	0.067	1.50	1.70
B	0.043	0.051	1.10	1.30
C	0.030	0.033	0.75	0.85
D	0.010	0.016	0.25	0.40
E	0.003	0.006	0.08	0.15
F	0.020	0.030	0.51	0.77

Mounting PAD Layout



## 8. Part Marking System



## 9. Package Information

Package	Type	Tape Width (mm)	Quantity(pcs)
SOD523	RB520S-30	8	3000



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